



帛江科技股份有限公司
BO-JIANG TECHNOLOGY CO., LTD.
PRODUCT SPECIFICATION (產品規格書)

| | | | |
|--------------|------------------------|----------|----------------|
| PART NO.(圖號) | 7865NR502BD000B | DATE(日期) | 2018 / 08 / 06 |
| TITLE(產品名稱) | SMA R/A PCB MOUNT JACK | | |

MATERIAL AND FINISH (材質及表面處理)

| DESCRIPTION(名稱) | MATERIAL(材質) | FINISH(表面處理) |
|----------------------|------------------|--------------|
| Center Contact(中心導體) | BERYLLIUM COPPER | 30μ" GOLD |
| Insulator(絕緣體) | PTFE | WHITE |
| Outer Contact(外導體) | BRASS | 3μ" GOLD |
| Others(其它) | | |

ELECTRICAL (電氣特性)

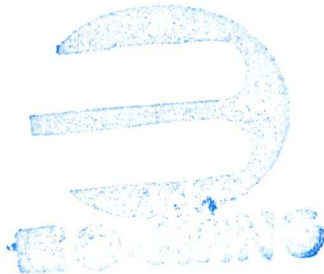
| ITEM(項目) | TEST CONDITION(測試條件) (at 25°C ±5°C) | SPECIFICATION(規格) |
|--|--|-------------------|
| Impedance(阻抗) | DC~ 12.4 GHz | 50 Ω |
| Voltage Standing Wave Ratio(VSWR)(駐波比) | DC~ 12.4 GHz | 1.5 Max. |
| Dielectric Withstanding Voltage(絕緣耐電壓) | AC, time: 60sec | 1000 Vrms Min. |
| Contact Resistance (導體阻抗) | Center Contact(中心導體) | DC 0.2V, 1A |
| | Outer Contact(外導體) | DC 0.2V, 1A |
| Insulation Resistance(絕緣阻抗) | DC 500V, time: 120sec | 5000 MΩ Min. |

MECHANICAL (機械特性)

| ITEM(項目) | TEST CONDITION(測試條件) | SPECIFICATION(規格) |
|-------------------------------------|----------------------|-------------------|
| Force To Engage/Disengage(接合力/脫離力): | N/A | 2 in-lbs. Max. |

REMARKS(備註)

1. HSF Compliant.
2. Between BODY And CUBE BODY Must Withstand 60 lbs. Min. Axial Force And 15 in-lbs. Min. Torque Force. (軸向力和扭力測試)。
3. Between BODY And INSULATOR Must Withstand 6 lbs. Min. Axial Force. (軸向力測試)。



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|-------------|--------------------------------------|----------------|---------------|-------------|
| D | 訂正電氣特性之測試條件 | | | |
| C | 修改部分欄位 | Karl | Alicia | Doris |
| B | 備註 2. 將 30 lbs. Min. 改為 60 lbs. Min. | Mark | Mark | Ariel |
| A | Original | Mark | Mark | Alicia |
| Issue 版本 | Revision 修改記錄 | Approved 核准 | Checked 審核 | Drawn 製定 |